

Thyristor Module

$$V_{RRM} = 1200 \text{ V}$$

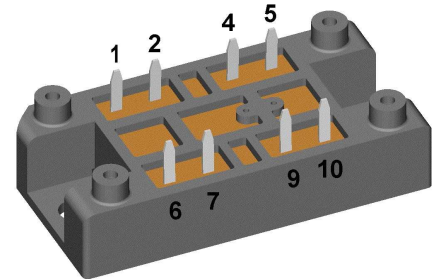
$$I_{TAV} = 27 \text{ A}$$

$$V_T = 1.28 \text{ V}$$

AC Controlling
 2~ full-controlled

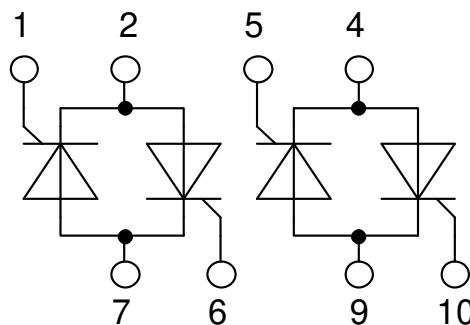
Part number

VW2x60-12io1



Backside: isolated

 E72873



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al₂O₃-ceramic

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: V1-A-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Disclaimer Notice

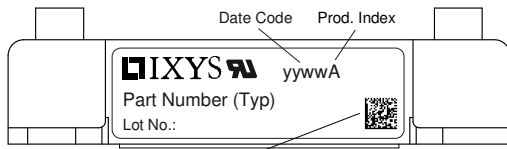
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| Rectifier | | | Ratings | | | |
|----------------|--|---|--------------------------|------|------|-------------------|
| Symbol | Definition | Conditions | min. | typ. | max. | Unit |
| $V_{RSM/DSM}$ | max. non-repetitive reverse/forward blocking voltage | $T_{VJ} = 25^{\circ}C$ | | | 1300 | V |
| $V_{RRM/DRM}$ | max. repetitive reverse/forward blocking voltage | $T_{VJ} = 25^{\circ}C$ | | | 1200 | V |
| I_{RD} | reverse current, drain current | $V_{R/D} = 1200 V$ | $T_{VJ} = 25^{\circ}C$ | | 100 | μA |
| | | $V_{R/D} = 1200 V$ | $T_{VJ} = 125^{\circ}C$ | | 5 | mA |
| V_T | forward voltage drop | $I_T = 40 A$ | $T_{VJ} = 25^{\circ}C$ | | 1.25 | V |
| | | $I_T = 80 A$ | | | 1.65 | V |
| | | $I_T = 40 A$ | $T_{VJ} = 125^{\circ}C$ | | 1.28 | V |
| | | $I_T = 80 A$ | | | 1.75 | V |
| I_{TAV} | average forward current | $T_C = 85^{\circ}C$ | $T_{VJ} = 125^{\circ}C$ | | 27 | A |
| I_{RMS} | RMS forward current per phase | 180° sine | | | 60 | A |
| V_{T0} | threshold voltage | } for power loss calculation only | $T_{VJ} = 125^{\circ}C$ | | 0.85 | V |
| r_T | slope resistance | | | | 11 | m Ω |
| R_{thJC} | thermal resistance junction to case | | | | 0.92 | K/W |
| R_{thCH} | thermal resistance case to heatsink | | | 0.3 | | K/W |
| P_{tot} | total power dissipation | | $T_C = 25^{\circ}C$ | | 110 | W |
| I_{TSM} | max. forward surge current | $t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$ | $T_{VJ} = 45^{\circ}C$ | | 520 | A |
| | | $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$ | $V_R = 0 V$ | | 560 | A |
| | | $t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$ | $T_{VJ} = 125^{\circ}C$ | | 440 | A |
| | | $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$ | $V_R = 0 V$ | | 475 | A |
| I^2t | value for fusing | $t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$ | $T_{VJ} = 45^{\circ}C$ | | 1.35 | kA ² s |
| | | $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$ | $V_R = 0 V$ | | 1.31 | kA ² s |
| | | $t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$ | $T_{VJ} = 125^{\circ}C$ | | 970 | A ² s |
| | | $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$ | $V_R = 0 V$ | | 940 | A ² s |
| C_J | junction capacitance | $V_R = 400 V \quad f = 1 \text{ MHz}$ | $T_{VJ} = 25^{\circ}C$ | | 64 | pF |
| P_{GM} | max. gate power dissipation | $t_p = 30 \mu s$ | $T_C = 125^{\circ}C$ | | 10 | W |
| | | $t_p = 300 \mu s$ | | | 5 | W |
| P_{GAV} | average gate power dissipation | | | | 0.5 | W |
| $(di/dt)_{cr}$ | critical rate of rise of current | $T_{VJ} = 125^{\circ}C; f = 50 \text{ Hz}$ | repetitive, $I_T = 45 A$ | | 100 | A/ μs |
| | | $t_p = 200 \mu s; di_G/dt = 0.45 A/\mu s;$ $I_G = 0.45 A; V = \frac{2}{3} V_{DRM}$ | non-repet., $I_T = 27 A$ | | 500 | A/ μs |
| $(dv/dt)_{cr}$ | critical rate of rise of voltage | $V = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty; \text{ method 1 (linear voltage rise)}$ | $T_{VJ} = 125^{\circ}C$ | | 1000 | V/ μs |
| V_{GT} | gate trigger voltage | $V_D = 6 V$ | $T_{VJ} = 25^{\circ}C$ | | 1.5 | V |
| | | | $T_{VJ} = -40^{\circ}C$ | | 1.6 | V |
| I_{GT} | gate trigger current | $V_D = 6 V$ | $T_{VJ} = 25^{\circ}C$ | | 100 | mA |
| | | | $T_{VJ} = -40^{\circ}C$ | | 200 | mA |
| V_{GD} | gate non-trigger voltage | $V_D = \frac{2}{3} V_{DRM}$ | $T_{VJ} = 125^{\circ}C$ | | 0.2 | V |
| I_{GD} | gate non-trigger current | | | | 5 | mA |
| I_L | latching current | $t_p = 10 \mu s$ | $T_{VJ} = 25^{\circ}C$ | | 450 | mA |
| | | $I_G = 0.45 A; di_G/dt = 0.45 A/\mu s$ | | | | |
| I_H | holding current | $V_D = 6 V \quad R_{GK} = \infty$ | $T_{VJ} = 25^{\circ}C$ | | 200 | mA |
| t_{gd} | gate controlled delay time | $V_D = \frac{1}{2} V_{DRM}$ | $T_{VJ} = 25^{\circ}C$ | | 2 | μs |
| | | $I_G = 0.45 A; di_G/dt = 0.45 A/\mu s$ | | | | |
| t_q | turn-off time | $V_R = 100 V; I_T = 20 A; V = \frac{2}{3} V_{DRM}$ $di/dt = 10 A/\mu s \quad dv/dt = 15 V/\mu s \quad t_p = 200 \mu s$ | $T_{VJ} = 100^{\circ}C$ | | 150 | μs |



| Package V1-A-Pack | | Ratings | | | | |
|-------------------|--|----------------------|------|------|------|------|
| Symbol | Definition | Conditions | min. | typ. | max. | Unit |
| I_{RMS} | RMS current | per terminal | | | 100 | A |
| T_{VJ} | virtual junction temperature | | -40 | | 125 | °C |
| T_{op} | operation temperature | | -40 | | 100 | °C |
| T_{stg} | storage temperature | | -40 | | 125 | °C |
| Weight | | | | 37 | | g |
| M_D | mounting torque | | 2 | | 2.5 | Nm |
| $d_{Spp/App}$ | creepage distance on surface / striking distance through air | terminal to terminal | 6.0 | | | mm |
| $d_{Spb/Apb}$ | | terminal to backside | 12.0 | | | mm |
| V_{ISOL} | isolation voltage | t = 1 second | 3600 | | | V |
| | | t = 1 minute | 3000 | | | V |



Data Matrix: Typ (1-19), DC+Prod.Index (20-25), FKT# (26-31)
leer (33), lld.# (33-36)

| Ordering | Ordering Number | Marking on Product | Delivery Mode | Quantity | Code No. |
|----------|-----------------|--------------------|---------------|----------|----------|
| Standard | VW2x60-12io1 | VW2x60-12io1 | Blister | 24 | 519000 |

Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 125^{\circ}C$

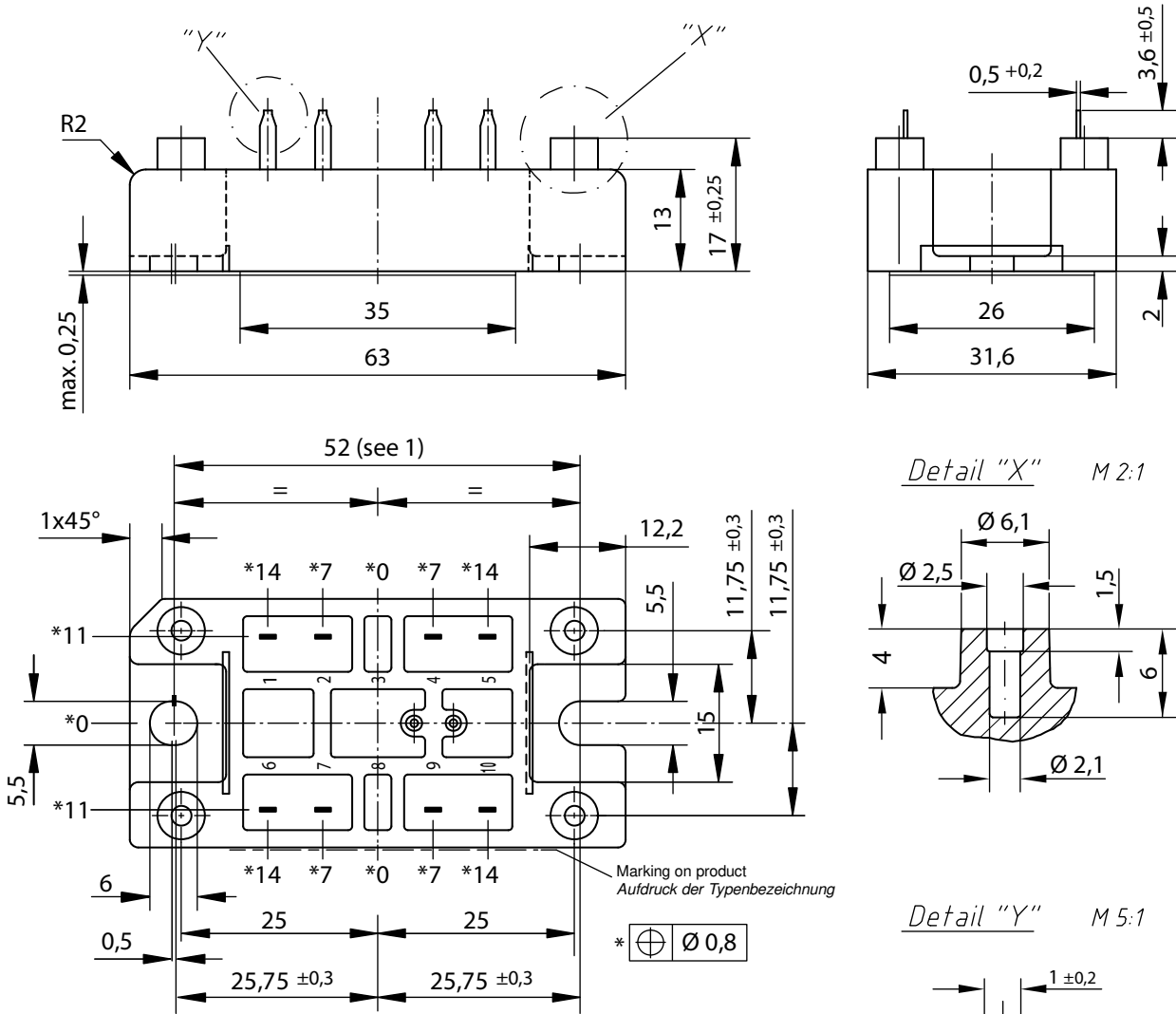


Thyristor

| | | | |
|--------------|--------------------|------|----|
| $V_{0\ max}$ | threshold voltage | 0.85 | V |
| $R_{0\ max}$ | slope resistance * | 8.5 | mΩ |

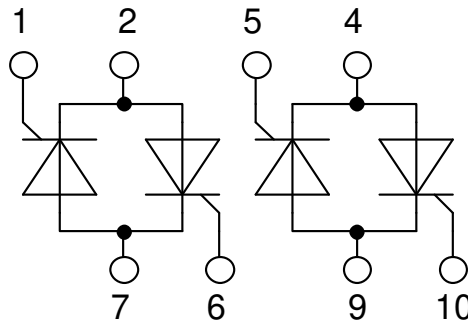


Outlines V1-A-Pack



Remarks / Bemerkungen:

1. Nominal distance mounting screws on heat sink: 52 mm / Nennabstand Befestigungsschrauben auf Kühlkörper: 52 mm
 2. General tolerance / Allgemeintoleranz: DIN ISO 2768 -T1-c
 3. Surface treatment of pins: tin plated (Sn) in hot dip / Oberflächenbehandlung der Pins: verzinkt (Sn) im Tauchbad
 4. Detail X:
EJOT PT® self-tapping screws (dimension K25) to be recommended for mounting on PCB
selbstschneidende Schraube (Größe K25) empfohlen für die PCB-Montage
- Take care on the maximum screw length according to board thickness and the maximum hole depth of 6 mm^L
Bei der Wahl der Schraubenlänge die PCB-Dicke und die maximale Lochtiefe von 6mm beachten
- Recommended mounting torque: 1.5 Nm / Empfohlenes Drehmoment: 1.5 Nm



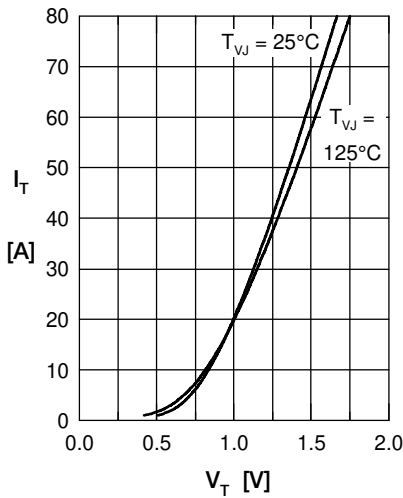
Thyristor


Fig. 1 Forward characteristics

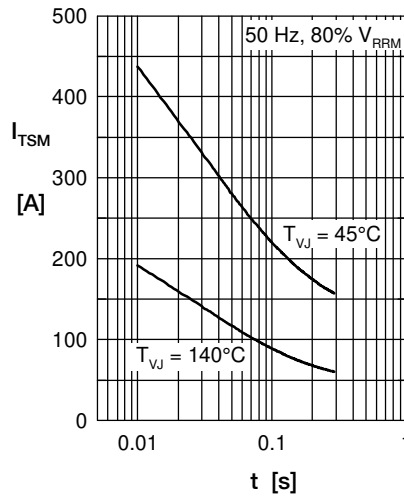
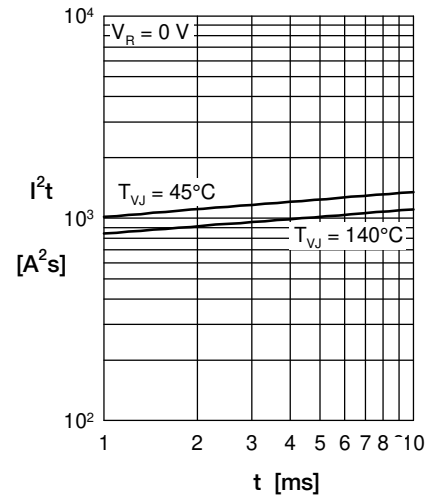
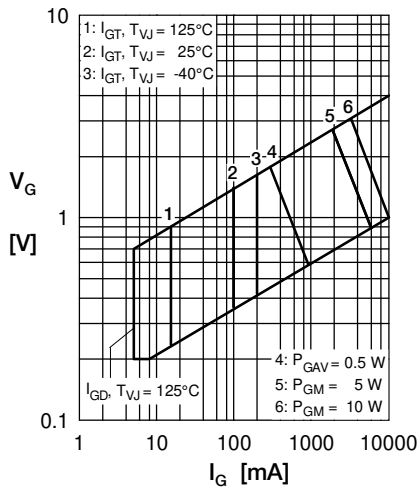

 Fig. 2 Surge overload current I_{TSM} ; crest value, t: duration

 Fig. 3 I^2t versus time (1-10 s)


Fig. 4 Gate voltage & gate current

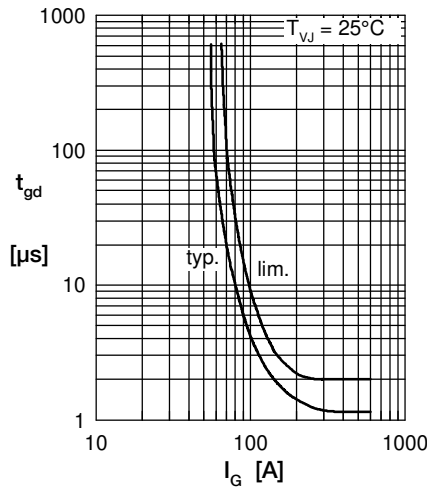
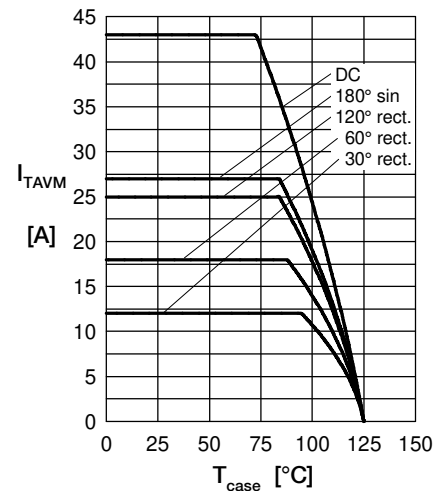

 Fig. 5 Gate controlled delay time t_{gd}


Fig. 6 Max. forward current at case temperature

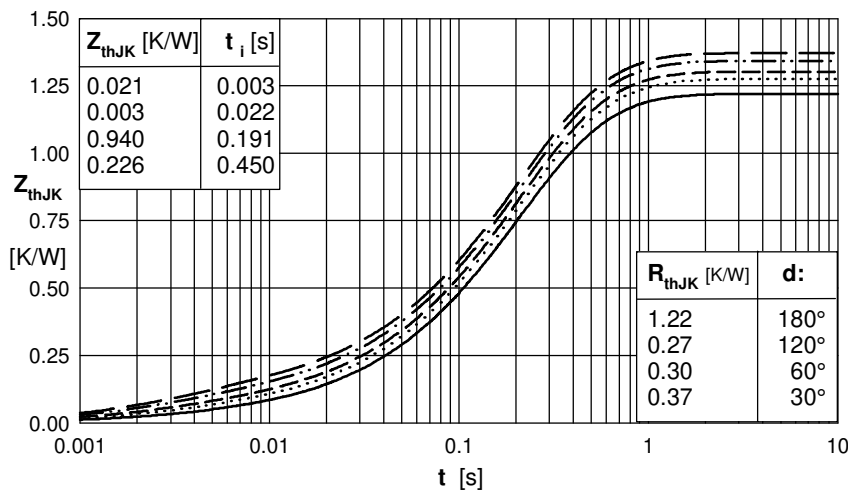


Fig. 7 Transient thermal impedance junction to heatsink (per thyristor)

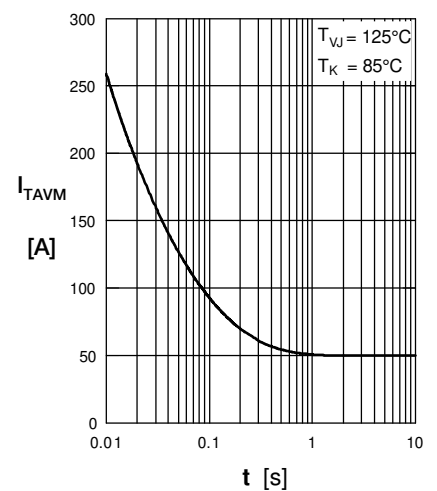


Fig. 8 Rated RMS current vs. time (360° conduction)